TO-252

Triac in a TO-252 Plastic Package.

Parameter	Symbol	Rating	Unit
Repetitive peak off-state/reverse voltages(T_j=125)	V_{DRM}/V_{RRM}	800	V
RMS on-state current(T_C=110)	$I_{T(RMS)}$	8	A
Non repetitive surge peak on-state current(full cycle, T_j=25°C)	$I_{TSM(t=20ms)}$	80	A
I^2t value for fusing(T_j=25)	$I^2t_{(tp=10ms)}$	32	A^2s
Critical rate of rise of on-state current (I_G =2I_{GT}, f=120Hz T_j=125)	dI/dt I-II-III	50	A/μs
Peak gate current(t_p =20μs T_j=125)	I_{GM}	4.0	A
Average gate power dissipation(T_j=125)	$P_{G(AV)}$	1.0	W
Operating junction temperature range	T_j	-40 125	
Storage junction temperature range	T_{stg}	-40 150	
Junction to ambient(AC)	$R_{th(j-a)}$	100	/W
Junction to case for(AC)	$R_{th(j-c)}$	3.1	

/ Package Dimensions

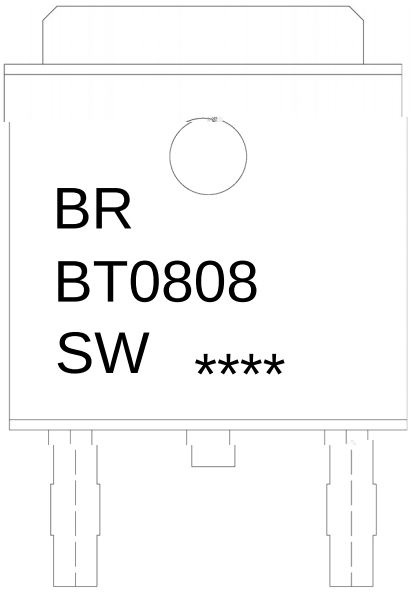


单位：mm

Symbol	Min	Max	Symbol	Min	Max
		6.25	A	2.20	2.40
b	0.50	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
		0.60			
D1	5.10	5.50	K	0.000	0.100

TO-252

/ Marking Instructions



BR

BT0808

SW I_{GT}

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Note:

BR:	Company Code
BT0808:	Product Type Code
SW:	I_{GT} Bracket code
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

				Note:
1	150	180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit：mm³)
	Units/Reel	Reels/Inner Box /	Units/Inner Box	Inner Boxes/Outer Box /	Units/Outer Box	Reel	Inner Box	Outer Box
TO-252	2,est	Conditions						